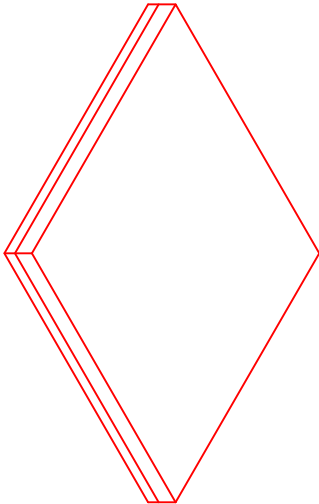


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REV.	DESCRIPTION	DATE	CHECKED	ORIGINATED BY
00	INITIAL RELEASE PER DCN C060097	06/06/99	E.B.	M.C.N.



7. REFERENCE SPECIFICATIONS:
A. AAWW SPEC #001-0691-2294: PACKING OPERATION PROCEDURE.
B. AAWW SPEC #001-0619-2062: MARKING.

6. PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BUMPS IS 144.
3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 12 X 12.
2. THE BASIC SOLDER BUMP GRID PITCH IS 1.00mm.
1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994.
- NOTES: UNLESS OTHERWISE SPECIFIED

TOLERANCES UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS			
DECIMAL	ANGULAR	±1°	
XX ±0.10			
XXX ±0.05			
XXXX ±0.03			
APPROVALS	DATE	TIME	
DESIGNER J. MICHERCH	04/14/99	1.00mm PITCH, LAMINATE SUBSTRATE, AAP	
CHECKER H. BOUTHAOUBA	04/14/99	13.00mm X 13.00mm, 2 LAYER.	
DATE 06/06/99	TIME 06/06/99	SCALE: 8:1	
DO NOT SCALE DRAWING			